

LNPT[™] STAT-KON[™] COMPOUND EJ000C

DESCRIPTION

LNP STAT-KON* EJ000C is a static dissipative compound based on Polyetherimide (PEI) resin containing carbon nanotubes. Added features of this grade include: LNP Clean Compounding Technology, Dimensional Stability. This material has a fit in broad range of markets including the semiconductor industry (e.g. HDD parts).

GENERAL INFORMATION

Features	Thermally Conductive, No PFAS intentionally added
Fillers	Carbon nanotube
Polymer Types	Polyetherimide (PEI)
Processing Techniques	Injection Molding

INDUSTRY

Electrical and Electronics

SUB INDUSTRY

Electronic Components, Mobile Phone - Computer - Tablets

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Modulus, 1 mm/min	3650	MPa	ISO 527
Tensile Stress, break, 50 mm/min	110	MPa	ISO 527
Tensile Strain, break, 50 mm/min	4	%	ISO 527
Flexural Modulus, 2 mm/min	3620	MPa	ISO 178
Flexural Strength, 2 mm/min	172	MPa	ISO 178
Tensile Modulus, 50 mm/min	3780	MPa	ASTM D638
Tensile Stress, brk, Type I, 50 mm/min	110	MPa	ASTM D638
Tensile Strain, brk, Type I, 50 mm/min	4	%	ASTM D638
Flexural Modulus, 1.3 mm/min, 50 mm span	3970	MPa	ASTM D790
Flexural Strength, 1.3 mm/min, 50 mm span	176	MPa	ASTM D790
IMPACT ⁽¹⁾			
Izod Impact, notched 80°10°4 +23°C	5	kJ/m ²	ISO 180/1A
Izod Impact, unnotched 80°10°4 +23°C	52	kJ/m ²	ISO 180/1U
Izod Impact, notched, 23°C	41	J/m	ASTM D256
Izod Impact, unnotched, 23°C	645	J/m	ASTM D4812
THERMAL ⁽¹⁾			
HDT/Af, 1.8 MPa Flatw 80°10°4 sp=64mm	201	°C	ISO 75/Af
HDT/Bf, 0.45 MPa Flatw 80°10°4 sp=64mm	211	°C	ISO 75/Bf
CTE, -40°C to 40°C, flow	4.0E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	4.0E-05	1/°C	ISO 11359-2
HDT, 1.82 MPa, 3.2mm, unannealed	201	°C	ASTM D648
HDT, 0.45 MPa, 3.2 mm, unannealed	211	°C	ASTM D648
PHYSICAL ⁽¹⁾			

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Melt Volume Rate, MVR at 320°C/10.0 kg	3.6	cm ³ /10 min	ISO 1133
Melt Volume Rate, MVR at 340°C/5.0 kg	2.5	cm ³ /10 min	ISO 1133
Melt Volume Rate, MVR at 360°C/5.0 kg	5.8	cm ³ /10 min	ISO 1133
Mold Shrinkage, flow	0.5 – 0.7	%	SABIC method
Mold Shrinkage, xflow	0.5 – 0.7	%	SABIC method
ELECTRICAL ⁽¹⁾			
Surface Resistivity	1E+04 – 1E+07	Ω	ASTM D257
Surface Resistivity	1E+04 – 1E+07	Ω	ANSI/ESD STM11.11
Volume Resistivity	1E+00 – 1E+02	Ω.cm	SABIC method
INJECTION MOLDING ⁽²⁾			
Drying Temperature	150	°C	
Drying Time	4 – 6	Hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	340 – 400	°C	
Rear - Zone 1 Temperature	340 – 380	°C	
Middle - Zone 2 Temperature	350 – 390	°C	
Front - Zone 3 Temperature	360 – 400	°C	
Nozzle Temperature	390 – 400	°C	
Mold Temperature	140 – 180	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw speed (Circumferential speed)	0.15 – 0.2	m/s	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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